Cerno™ Series: Model 103IL

Selective Soldering System with Advanced Process Controls

Features and Benefits

- Selective soldering of printed circuit boards as large as 610 x 457 mm (24.0 x 18.0 in.)
- Interchangeable solder pots and pumps compatible with tin-lead, lead-free and HMP solder alloys
- Choice of single selective solder nozzle, dual selective nozzles with independent control or 75 mm wide wave soldering nozzle
- SWAK-OS graphics-based programming and machine control software enables fast and straightforward program creation
- Optional in-line flux and preheat module with concurrent fluxing and preheating provides increased throughput

The Cerno™ 103IL is a robust selective soldering system delivering an exceptional combination of versatility, productivity and value. The Cerno™ 103IL has many unique features, including high speed Z-axis motion for faster processing time and reduced soldering cycle.

Flexibility. With its feature rich, graphics-based programming and machine control software, the Cerno™ 103IL is specially designed for demanding selective soldering applications. Set-up and time to first article is significantly reduced to within 10-15 minutes. The SWAK-OS software features seamless fiducial recognition, live teach cameras, real time data collection, SQL backend data extraction and complete FIS capability for shop floor integration.



SWAK-OS graphics-based programming software



Soldering Technology. With its flexible configuration, the Cerno™ 103IL is a versatile selective soldering system capable of processing tinlead, lead-free or HMP solder alloys. Interchangeable solder pots and pumps are available with either single selective solder nozzle, dual selective nozzles with independent control or 75 mm (3.0 in.) wide wave soldering nozzle. The nitrogen inerted dual nozzle system enables the use of multiple size nozzles within the same program further enhancing flexibility and productivity.

Process Control. Nordson SELECT's closed-loop rotary encoders and other advanced process control capabilities have been incorporated into the Cerno™ 103IL, enhancing solder quality, precision and yield capabilities.

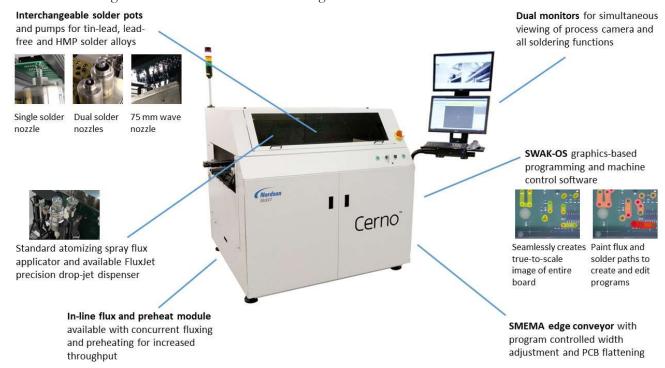
Value. With a reputation for innovation, comprehensive process solutions from Nordson SELECT ensure a maximum return on investment and low cost of ownership. From initial process development through full-scale production, you are supported by our experienced worldwide engineering, applications development and technical service network.



Cerno™ 103IL Features

The CernoTM 103IL is a fully configured SMEMA compatible selective soldering system and is a reliable and cost-effective solution for many demanding through-hole and SMT mixed-technology soldering applications including:

- O Printed circuit board assemblies and other solderable substrates
- o Interchangeable tin-lead and lead-free soldering



Standard Features

SMEMA edge conveyor with program controlled width adjustment, positive PCB location and PCB flattening Conveyor direction left-to-right

High speed Z-axis motion

Closed-loop rotary encoders

Atomizing spray flux applicator

Tin-lead solder pot and pump assembly with full set of quick change magnetically coupled bullet nozzles

Automatic solder pot level monitoring and fill system Automatic wave height monitoring and adjust system Solder alloy verification system

Heated nitrogen inerting system

Programming and fiducial alignment look-up camera

Dual process witness cameras

SWAK-OS graphics-based programming and machine control software

- Automatic fiducial alignment
- Board warp compensation
- On-board help videos
- Remote machine diagnostics
- Complete FIS capability

Off-line programming software

Dual monitors

Optional Features

Right-to-left conveyor direction

FluxJet precision drop-jet dispenser

In-process flux verification system for drop-jet

Dual flux heads, 2 atomizing spray heads, 2 drop-jet flux dispensers or one of each

Topside infrared preheater with closed-loop control

In-line flux and preheat module with concurrent fluxing and preheating

Automatic solder nozzle tinning system

Lead-free solder pot and pump assembly (titanium)

HMP solder pot and pump assembly

Dual nozzle solder pot and pump assembly, tin-lead or lead-free (titanium)

3-25 mm bullet nozzles or 4-25 mm mini-wave nozzles 75 mm (3.0 in.) wide wave nozzle and pump assembly, tin-lead or lead-free (titanium)

Solder pot exchange cart with warming controls

Bottom-side nitrogen spot preheater

Nitrogen de-bridging knife

Single monitor

Six channel thermal data logging system

Barcode reader



Specifications: Cerno™ 103IL

Motion System

 $\begin{array}{ll} Z \ accuracy & \pm 50 \ \mu m \ (0.002 \ in.) \\ Z \ repeatability \ ^{(1)} : & \pm 50 \ \mu m \ (0.002 \ in.), \ 3 \ sigma \\ Z \ velocity : & 0.15 \ m/s \ peak \ (6 \ in./s) \\ X-Y \ accuracy & \pm 50 \ \mu m \ (0.002 \ in.) \end{array}$

X-Y repeatability (1): $\pm 50 \mu m$ (0.002 in.), 3 sigma X-Y velocity: 0.2 m/s peak (8 in./s)

Computer

PC with Windows® operating system

Software

SWAK-OS graphics-based programming and machine control software

Solder Pot Capacity and Weight

Capacity (2): Approx. 13.6 kg (30.0 lbs.)

Total weight of tin-lead solder together with solder pot and pump assembly (2): Approx. 24.0 kg (53.0 lbs.)

Total weight of lead-free solder together with solder pot and pump assembly (2): Approx. 21.3 kg (47.0 lbs.)

Solderable Area (X-Y)

Single bullet, dual bullet or mini-wave nozzles (3,4):

Max. 610 x 457 mm (24.0 x 18.0 in.) Min. 50 x 50 mm (2.0 x 2.0 in.)

Board Handling Capability

Max. board size: 610 x 457 mm (24.0 x 18.0 in.) Min. board size: 50 x 50 mm (2.0 x 2.0 in.)

Conveyor

Max. board/carrier length:

Min. board/carrier length:

Max. board/carrier width:

Min. board/carrier width:

Min. board/carrier width:

Max. board/carrier thickness:

Max. overboard clearance:

Max. underboard clearance:

Max. underboard clearance:

Max. board/carrier thickness:

102 mm (4.0 in.)

Edge clearance (5): 3 mm (0.12 in.), edge conveyor

including on-rail clamps

Transport height: Conforms to SMEMA standard

for conveyor height; height adjustable from 940-965 mm (37.0 - 38.0 in.) from floor to

bottom of board

Load capacity (6): 4.5 kg (10.0 lbs.)

Operation modes: Automatic (SMEMA), manual or

pass-through

Facilities Requirements

System footprint: 1701 x 1421 mm (66.9 x 55.9 in.)
Air supply: Less than 10 CFH @ 90-100 psi

Power (mains) (7): Power supply accommodates 120VAC, 60 Hz,

15 A standard or 208/220-240VAC, 60 Hz

single phase, 15 A optional 50 A with topside preheating (8)

Nitrogen (9): 99.999% pure @ 60-100 psi, 30-60 CFH

consumption

Ventilation: Rear 250 CFM recommended, two 100 mm

(4.0 in.) dia. ducts

System weight (10, 11):431 kg (950 lbs.)

- (1) Repeatability is measured at full rated system speed.
- (2) Solder capacity and total weight of solder pot and pump assembly varies depending on solder alloy.
- (3) Substrates as small as 50 x 50 mm (2.0 x 2.0 in.) are possible without the need for fixturing or other tooling.
- (4) Contact factory regarding smaller boards/carriers.
- Edge conveyor conforms to SMEMA standards.
- (6) Total weight of all parts on conveyor at any one time. Contact factory regarding requirements for greater load capacity.
- (7) Electrical power varies depending on configuration.
- (8) Topside preheating only available with 208/220-240VAC, 60 Hz, single phase power supply.
- (9) Nitrogen consmption is solder nozzle dependent and machine configuration dependent.
- (10) System weight varies depending on configuration.
- (11) Configuration dependent. Other configurations may be available. Contact Nordson SELECT.

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Standards Compliance

SMEMA

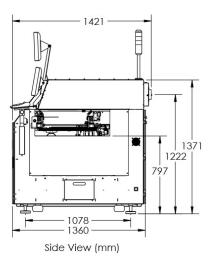
Additional options may be available: contact Nordson SELECT for further information.



Cerno™ 103IL

Dimensions are in millimeters

1883 1889 1084 1289 1395 Front View (mm)



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Published 2017-27-11

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